
HB56A232D-5/6/7

2,097,152-word \times 32-bit High Density Dynamic RAM Module

HITACHI

ADE-203-749A (Z)

Rev.1.0

Feb. 27, 1997

Description

The HB56A232D is a 2M \times 32 dynamic RAM Small Outline Dual In-line Memory Module (S.O.DIMM), mounted 4 pieces of 16-Mbit DRAM (HM5117800) sealed in TSOP package. An outline of the HB56A232D is 72-pin Zig Zag Dual tabs socket type compact and thin package. Therefore, the HB56A232D makes high density mounting possible without surface mount technology. The HB56A232D provides common data inputs and outputs. Decoupling capacitors are mounted on the module board.

Features

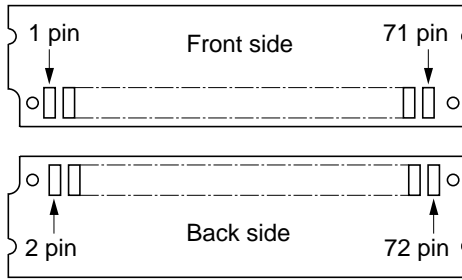
- 72-pin Zig Zag Dual tabs socket type
 - Outline: 59.69 mm (Length) \times 25.40 mm (Height) \times 2.42 mm (Thickness)
 - Lead pitch: 1.27 mm
- Single 5 V ($\pm 5\%$) supply
- High speed
 - Access time: $t_{\text{RAC}} = 50/60/70$ ns (max)
 - $t_{\text{CAC}} = 13/15/18$ ns (max)
- Low power dissipation
 - Active mode: 2.31/2.10/1.89 W (max)
 - Standby mode (TTL): 42 mW (max)
 - (CMOS): 3.15 mW (max) (L-version)
- Fast page mode capability
- Refresh period
 - 2048 refresh cycles: 32 ms
 - 128 ms (L-version)
- 4 variations of refresh
 - $\overline{\text{RAS}}$ -only refresh
 - $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh
 - Hidden refresh
 - Self refresh (L-version)
- TTL compatible

HB56A232D-5/6/7

Ordering Information

Type No.	Access time	Package	Contact pad
HB56A232D-5	50 ns	72-pin small outline DIMM	Gold
HB56A232D-6	60 ns		
HB56A232D-7	70 ns		
HB56A232D-5L	50 ns		
HB56A232D-6L	60 ns		
HB56A232D-7L	70 ns		

Pin Arrangement



Front side				Back side			
Pin No.	Pin name	Pin No.	Pin name	Pin No.	Pin name	Pin No.	Pin name
1	V _{SS}	37	DQ18	2	DQ0	38	DQ19
3	DQ1	39	V _{SS}	4	DQ2	40	$\overline{\text{CE}}0$
5	DQ3	41	$\overline{\text{CE}}2$	6	DQ4	42	$\overline{\text{CE}}3$
7	DQ5	43	$\overline{\text{CE}}1$	8	DQ6	44	$\overline{\text{RE}}0$
9	DQ7	45	NC	10	V _{CC}	46	NC
11	PD1	47	$\overline{\text{WE}}$	12	A0	48	NC
13	A1	49	DQ20	14	A2	50	DQ21
15	A3	51	DQ22	16	A4	52	DQ23
17	A5	53	DQ24	18	A6	54	DQ25
19	A10	55	NC	20	NC	56	DQ27
21	DQ9	57	DQ28	22	DQ10	58	DQ29
23	DQ11	59	DQ31	24	DQ12	60	DQ30
25	DQ13	61	V _{CC}	26	DQ14	62	DQ32
27	DQ15	63	DQ33	28	A7	64	DQ34
29	NC	65	NC	30	V _{CC}	66	PD2
31	A8	67	PD3	32	A9	68	PD4
33	NC	69	PD5	34	$\overline{\text{RE}}2$	70	PD6
35	DQ16	71	PD7	36	NC	72	V _{SS}

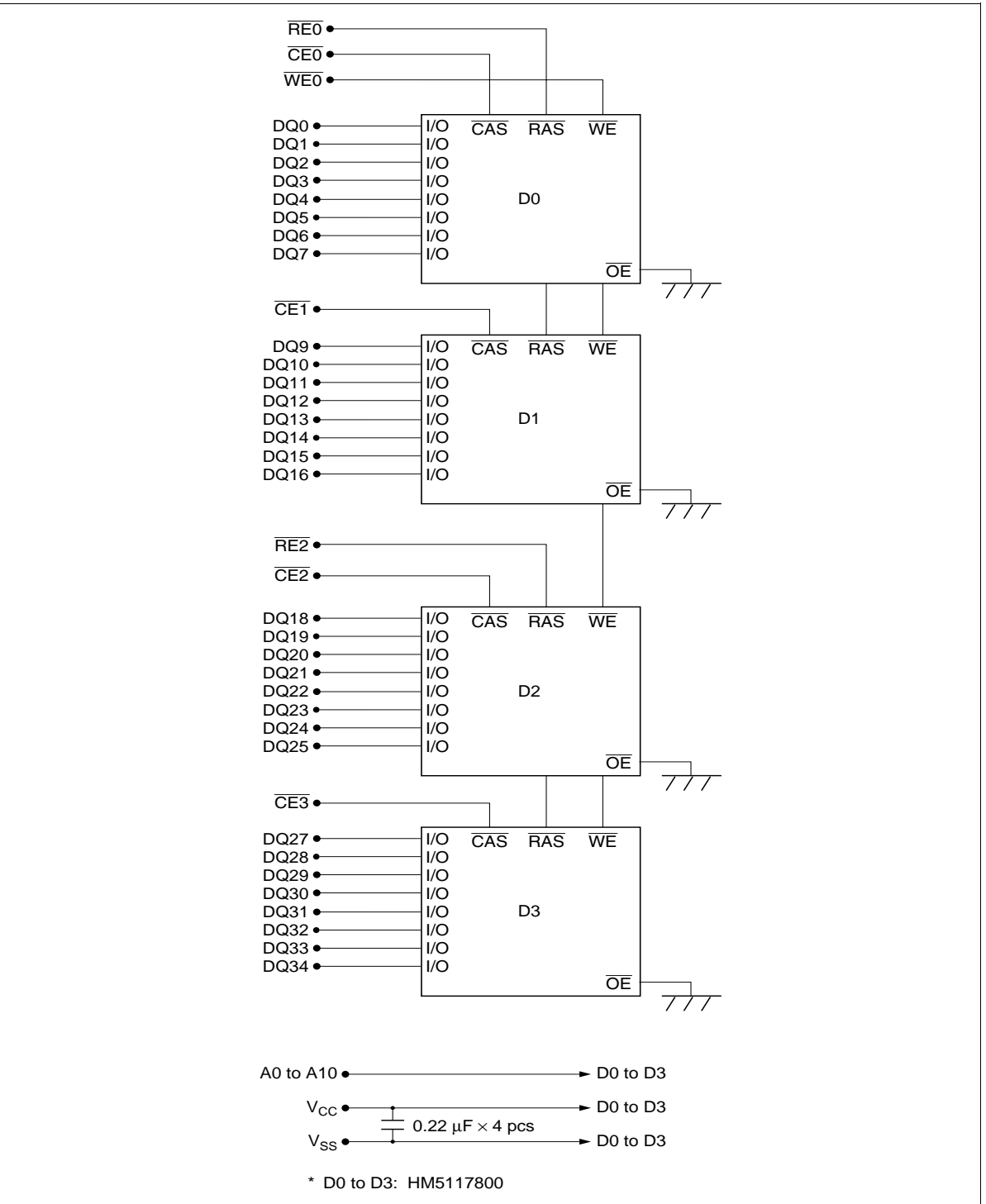
Pin Description

Pin name	Function
A0 to A10	Address inputs: — Row address: A0 to A10 — Column address: A0 to A9 — Refresh address: A0 to A10
DQ0 to DQ7, DQ9 to DQ16, DQ18 to DQ25, DQ27 to DQ34	Data-in/Data-out
$\overline{RE0}$, $\overline{RE2}$	Row address strobe (\overline{RAS})
$\overline{CE0}$ to $\overline{CE3}$	column address strobe (\overline{CAS})
\overline{WE}	Read/Write enable
V_{CC}	Power supply
V_{SS}	Ground
PD1 to PD7	Presence detect
NC	No connection

Presence Detect Pin Arrangement

Pin No.	Pin name	Function		
		50 ns	60 ns	70 ns
11	PD1	V_{SS}	V_{SS}	V_{SS}
66	PD2	NC	NC	NC
67	PD3	V_{SS}	V_{SS}	V_{SS}
68	PD4	NC	NC	NC
69	PD5	V_{SS}	NC	V_{SS}
70	PD6	V_{SS}	NC	NC
71	PD7	NC	NC	NC
	PD7 (L-version)	V_{SS}	V_{SS}	V_{SS}

Block Diagram



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Voltage on any pin relative to V_{SS}	V_T	-1.0 to +7.0	V
Supply voltage relative to V_{SS}	V_{CC}	-1.0 to +7.0	V
Short circuit output current	I_{out}	50	mA
Power dissipation	P_t	4	W
Operating temperature	T_{opr}	0 to +70	°C
Storage temperature	T_{stg}	-55 to +125	°C

Recommended DC Operating Conditions ($T_a = 0$ to 70°C)

Parameter	Symbol	Min	Typ	Max	Unit	Note
Supply voltage	V_{SS}	0	0	0	V	
	V_{CC}	4.75	5.0	5.25	V	1
Input high voltage	V_{IH}	2.4	—	5.5	V	1
Input low voltage	V_{IL}	-1.0	—	0.8	V	1

Note: 1. All voltage referred to V_{SS} .

DC Characteristics ($T_a = 0$ to 70°C , $V_{CC} = 5\text{ V} \pm 5\%$, $V_{SS} = 0\text{ V}$)

Parameter	Symbol	50 ns		60 ns		70 ns		Unit	Test conditions	Notes
		Min	Max	Min	Max	Min	Max			
Operating current	I_{CC1}	—	440	—	400	—	360	mA	$t_{RC} = \text{min}$	1, 2
Standby current	I_{CC2}	—	8	—	8	—	8	mA	TTL interface $\overline{\text{RAS}}, \overline{\text{CAS}} = V_{IH}$ Dout = High-Z	
		—	4	—	4	—	4	mA	CMOS interface $\overline{\text{RAS}}, \overline{\text{CAS}} \geq V_{CC} - 0.2\text{ V}$ Dout = High-Z	
Standby current (L-version)	I_{CC2}	—	0.6	—	0.6	—	0.6	mA	CMOS interface $\overline{\text{RAS}}, \overline{\text{CAS}} \geq V_{CC} - 0.2\text{ V}$ Dout = High-Z	
$\overline{\text{RAS}}$ -only refresh current	I_{CC3}	—	440	—	400	—	360	mA	$t_{RC} = \text{min}$	2
Standby current	I_{CC5}	—	20	—	20	—	20	mA	$\overline{\text{RAS}} = V_{IH}, \overline{\text{CAS}} = V_{IL}$ Dout = enable	1
$\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh current	I_{CC6}	—	440	—	400	—	360	mA	$t_{RC} = \text{min}$	
Fast page mode current	I_{CC7}	—	400	—	360	—	340	mA	$t_{PC} = \text{min}$	1, 3
Battery backup current (Standby with CBR refresh) (L-version)	I_{CC10}	—	2	—	2	—	2	mA	CMOS interface Dout = High-Z CBR refresh: $t_{RC} = 62.5\ \mu\text{s}$ $t_{RAS} \leq 0.3\ \mu\text{s}$	4
Self refresh mode current (L-version)	I_{CC11}	—	1.2	—	1.2	—	1.2	mA	CMOS interface $\overline{\text{RAS}}, \overline{\text{CAS}} \leq 0.2\text{ V}$ Dout = High-Z	
Input leakage current	I_{LI}	-10	10	-10	10	-10	10	μA	$0\text{ V} \leq V_{in} \leq 5.5\text{ V}$	
Output leakage current	I_{LO}	-10	10	-10	10	-10	10	μA	$0\text{ V} \leq V_{out} \leq 5.5\text{ V}$ Dout = disable	
Output high voltage	V_{OH}	2.4	V_{CC}	2.4	V_{CC}	2.4	V_{CC}	V	High Iout = -5 mA	
Output low voltage	V_{OL}	0	0.4	0	0.4	0	0.4	V	Low Iout = 4.2 mA	

- Notes:
- I_{CC} depends on output load condition when the device is selected, I_{CC} max is specified at the output open condition.
 - Address can be changed once or less while $\overline{\text{RAS}} = V_{IL}$.
 - Address can be changed once or less while $\overline{\text{CAS}} = V_{IH}$.
 - $\overline{\text{CAS}} = L$ ($\leq 0.2\text{ V}$) while $\overline{\text{RAS}} = L$ ($\leq 0.2\text{ V}$).

Capacitance ($T_a = 25^\circ\text{C}$, $V_{CC} = 5\text{ V} \pm 5\%$)

Parameter	Symbol	Typ	Max	Unit	Notes
Input capacitance (Address)	C_{i1}	—	40	pF	1
Input capacitance (\overline{WE})	C_{i2}	—	48	pF	1
Input capacitance (\overline{RAS})	C_{i3}	—	30	pF	1
Input capacitance (\overline{CAS})	C_{i4}	—	23	pF	1
I/O capacitance (DQ)	$C_{i/O}$	—	23	pF	1, 2

Notes: 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.

2. $\overline{CAS} = V_{IH}$ to disable Dout.

AC Characteristics ($T_a = 0$ to 70°C , $V_{CC} = 5\text{ V} \pm 5\%$, $V_{SS} = 0\text{ V}$) *¹, *², *¹⁷**Test Conditions**

- Input rise and fall times: 5 ns
- Input timing reference levels: 0.8 V, 2.4 V
- Output timing reference levels: 0.4 V, 2.4 V
- Output load: 2 TTL gate + C_L (100 pF) (Including scope and jig)

Read, Write, and Refresh Cycles (Common parameters)

Parameter	Symbol	50 ns		60 ns		70 ns		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Random read or write cycle time	t_{RC}	90	—	110	—	130	—	ns	
\overline{RAS} precharge time	t_{RP}	30	—	40	—	50	—	ns	
\overline{CAS} precharge time	t_{CP}	7	—	10	—	10	—	ns	
\overline{RAS} pulse width	t_{RAS}	50	10000	60	10000	70	10000	ns	
\overline{CAS} pulse width	t_{CAS}	13	10000	15	10000	18	10000	ns	
Row address setup time	t_{ASR}	0	—	0	—	0	—	ns	
Row address hold time	t_{RAH}	7	—	10	—	10	—	ns	
Column address setup time	t_{ASC}	0	—	0	—	0	—	ns	
Column address hold time	t_{CAH}	7	—	10	—	15	—	ns	
\overline{RAS} to \overline{CAS} delay time	t_{RCD}	17	37	20	45	20	52	ns	3
\overline{RAS} to column address delay time	t_{RAD}	12	25	15	30	15	35	ns	4
\overline{RAS} hold time	t_{RSH}	13	—	15	—	18	—	ns	
\overline{CAS} hold time	t_{CSH}	50	—	60	—	70	—	ns	
\overline{CAS} to \overline{RAS} precharge time	t_{CRP}	5	—	5	—	5	—	ns	
\overline{CAS} delay time from Din	t_{DZC}	0	—	0	—	0	—	ns	
Transition time (rise and fall)	t_T	3	50	3	50	3	50	ns	5
Refresh period (2,048 cycles)	t_{REF}	—	32	—	32	—	32	ms	
Refresh period (2,048 cycles) (L-version)	t_{REF}	—	128	—	128	—	128	ms	

Read Cycle

Parameter	Symbol	50 ns		60 ns		70 ns		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Access time from $\overline{\text{RAS}}$	t_{RAC}	—	50	—	60	—	70	ns	6, 7
Access time from $\overline{\text{CAS}}$	t_{CAC}	—	13	—	15	—	18	ns	7, 8, 15
Access time from address	t_{AA}	—	25	—	30	—	35	ns	7, 9, 15
Read command setup time	t_{RCS}	0	—	0	—	0	—	ns	
Read command hold time to $\overline{\text{CAS}}$	t_{RCH}	0	—	0	—	0	—	ns	10
Read command hold time to $\overline{\text{RAS}}$	t_{RRH}	5	—	5	—	5	—	ns	10
Column address to $\overline{\text{RAS}}$ lead time	t_{RAL}	25	—	30	—	35	—	ns	
Column address to $\overline{\text{CAS}}$ lead time	t_{CAL}	25	—	30	—	35	—	ns	
$\overline{\text{CAS}}$ to output in low-Z	t_{CLZ}	0	—	0	—	0	—	ns	
Output data hold time	t_{OH}	3	—	3	—	3	—	ns	
Output buffer turn-off time	t_{OFF}	—	13	—	15	—	15	ns	11
$\overline{\text{CAS}}$ to Din delay time	t_{CDD}	13	—	15	—	18	—	ns	

Write Cycle

Parameter	Symbol	50 ns		60 ns		70 ns		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Write command setup time	t_{WCS}	0	—	0	—	0	—	ns	12
Write command hold time	t_{WCH}	7	—	10	—	15	—	ns	
Write command pulse width	t_{WCP}	7	—	10	—	10	—	ns	
Data-in setup time	t_{DS}	0	—	0	—	0	—	ns	13
Data-in hold time	t_{DH}	7	—	10	—	15	—	ns	13

Refresh Cycle

Parameter	Symbol	50 ns		60 ns		70 ns		Unit	Notes
		Min	Max	Min	Max	Min	Max		
$\overline{\text{CAS}}$ setup time (CBR refresh cycle)	t_{CSR}	5	—	5	—	5	—	ns	
$\overline{\text{CAS}}$ hold time (CBR refresh cycle)	t_{CHR}	7	—	10	—	10	—	ns	
$\overline{\text{WE}}$ setup time (CBR refresh cycle)	t_{WRP}	0	—	0	—	0	—	ns	
$\overline{\text{WE}}$ hold time (CBR refresh cycle)	t_{WRH}	7	—	10	—	10	—	ns	
$\overline{\text{RAS}}$ precharge to $\overline{\text{CAS}}$ hold time	t_{RPC}	5	—	5	—	5	—	ns	

Fast Page Mode Cycle

Parameter	Symbol	50 ns		60 ns		70 ns		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Fast page mode cycle time	t_{PC}	35	—	40	—	45	—	ns	
Fast page mode $\overline{\text{RAS}}$ pulse width	t_{RASP}	—	100000	—	100000	—	100000	ns	14
Access time from $\overline{\text{CAS}}$ precharge	t_{CPA}	—	30	—	35	—	40	ns	7, 15
$\overline{\text{RAS}}$ hold time from $\overline{\text{CAS}}$ precharge	t_{CPRH}	30	—	35	—	40	—	ns	

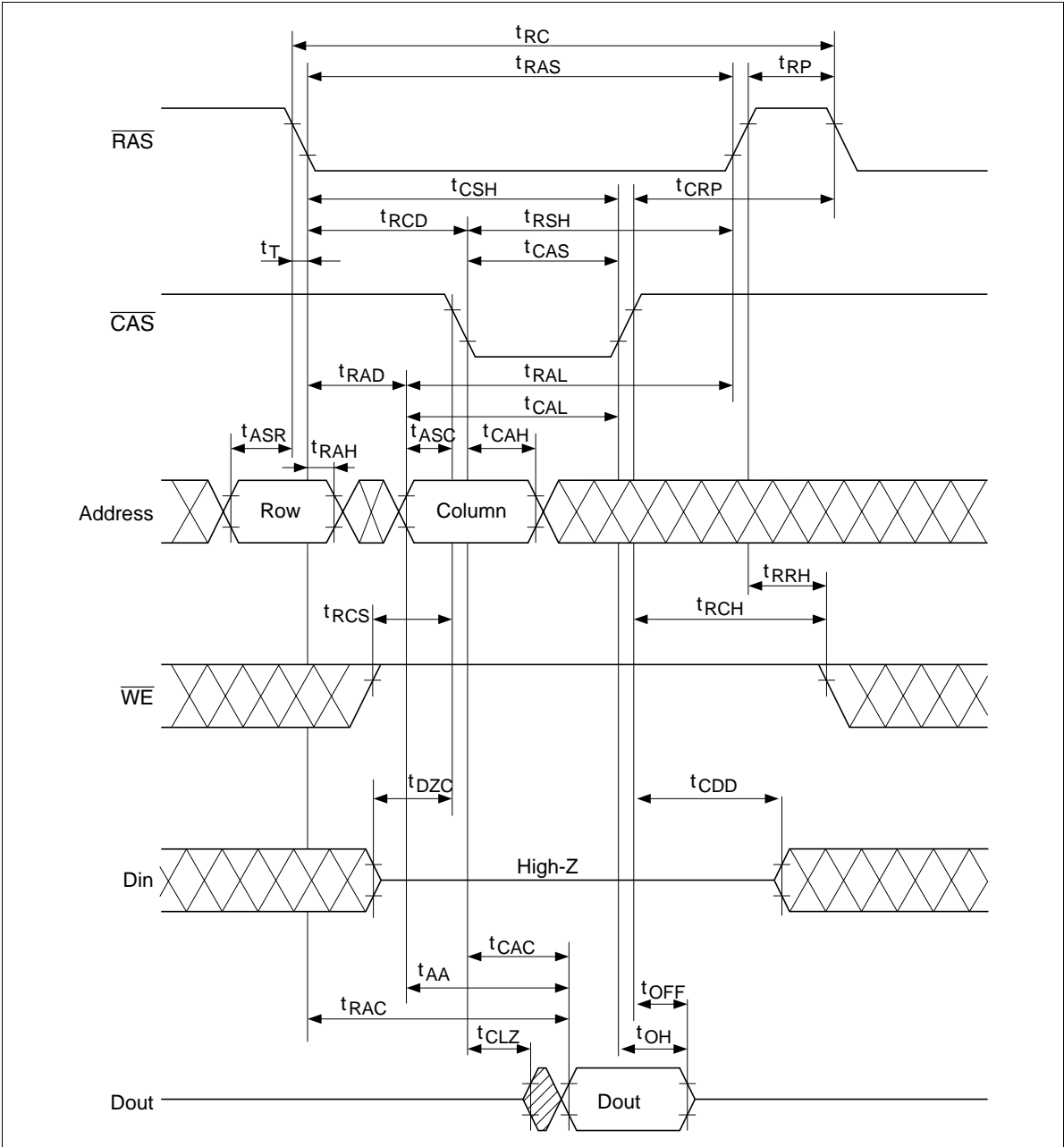
Self Refresh Mode (L-version)

Parameter	Symbol	50 ns		60 ns		70 ns		Unit	Notes
		Min	Max	Min	Max	Min	Max		
$\overline{\text{RAS}}$ pulse width (Self refresh)	t_{RASS}	100	—	100	—	100	—	μs	
$\overline{\text{RAS}}$ precharge time (Self refresh)	t_{RPS}	90	—	110	—	130	—	ns	
$\overline{\text{CAS}}$ hold time (Self refresh)	t_{CHS}	-50	—	-50	—	-50	—	ns	

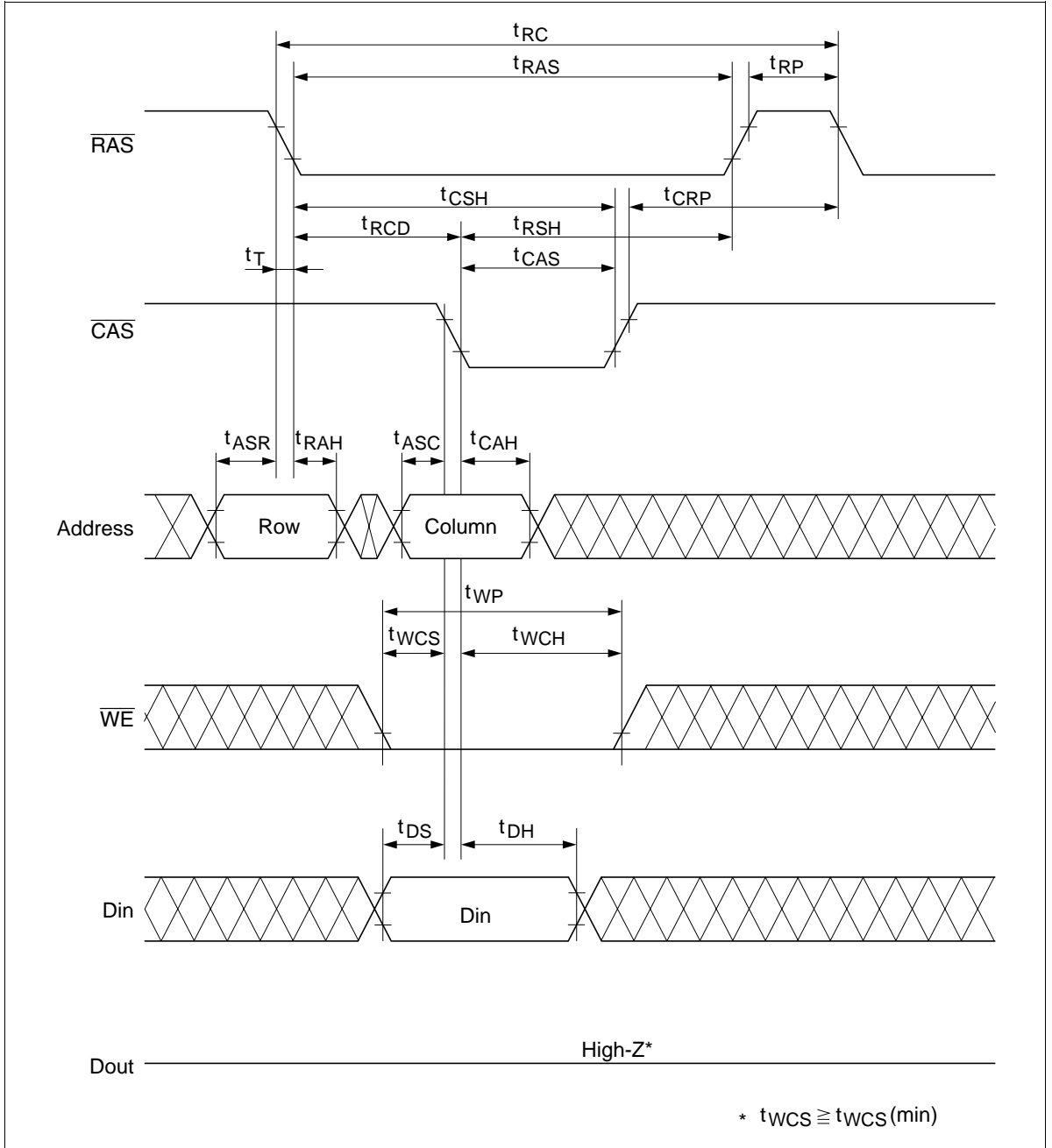
- Notes:
1. AC measurements assume $t_r = 5$ ns.
 2. An initial pause of 200 μ s is required after power up followed by a minimum of eight initialization cycles (any combination of cycles containing $\overline{\text{RAS}}$ -only refresh cycle or $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh). If the internal refresh counter is used, a minimum of eight $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh cycles are required.
 3. Operation with the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC} .
 4. Operation with the t_{RAD} (max) limit insures that t_{RAC} (max) can be met, t_{RAD} (max) is specified as a reference point only; if t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled exclusively by t_{AA} .
 5. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} (min) and V_{IL} (max).
 6. Assumes that $t_{\text{RCD}} \leq t_{\text{RCD}}$ (max) and $t_{\text{RAD}} \leq t_{\text{RAD}}$ (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
 7. Measured with a load circuit equivalent to 2 TTL loads and 100 pF.
 8. Assumes that $t_{\text{RCD}} \geq t_{\text{RCD}}$ (max) and $t_{\text{RCD}} + t_{\text{CAC}}$ (max) $\geq t_{\text{RAD}} + t_{\text{AA}}$ (max).
 9. Assumes that $t_{\text{RAD}} \geq t_{\text{RAD}}$ (max) and $t_{\text{RCD}} + t_{\text{CAC}}$ (max) $\leq t_{\text{RAD}} + t_{\text{AA}}$ (max).
 10. Either t_{RCH} or t_{RRH} must be satisfied for a read cycles.
 11. t_{OFF} (max) defines the time at which the outputs achieve the open circuit condition and are not referred to output voltage levels.
 12. Early write cycle only ($t_{\text{WCS}} \geq t_{\text{WCS}}$ (min)).
 13. These parameters are referred to $\overline{\text{CAS}}$ leading edge in early write cycles.
 14. t_{RASP} defines $\overline{\text{RAS}}$ pulse width in Fast page mode cycles.
 15. Access time is determined by the longest among t_{AA} , t_{CAC} and t_{CPA} .
 16. When output buffers are enabled once, sustain the low impedance state until valid data is obtained. When output buffer is turned on and off within a very short time, generally it causes large $V_{\text{CC}} / V_{\text{SS}}$ line noise, which causes to degrade V_{IH} min./ V_{IL} max level.
 17. All the V_{CC} and V_{SS} pins shall be supplied with the same voltages.
 18. Please do not use t_{RASS} timing, $10 \mu\text{s} \leq t_{\text{RASS}} \leq 100 \mu\text{s}$. During this period, the device is in transition state from normal operation mode to self refresh mode. If $t_{\text{RASS}} \geq 100 \mu\text{s}$, then $\overline{\text{RAS}}$ precharge time should use t_{RPS} instead of t_{RP} .
 19. If you use distributed CBR refresh mode with 15.6 μs interval in normal read/write cycle, CBR refresh should be executed within 15.6 μs immediately after exiting from and before entering into self refresh mode.
 20. If you use $\overline{\text{RAS}}$ only refresh or CBR burst refresh mode in normal read/write cycle, 2048 cycles of distributed CBR refresh with 15.6 μs interval should be executed within 32 ms immediately after exiting from and before entering into the self refresh mode.
 21. Repetitive self refresh mode without refreshing all memory is not allowed. Once you exit from self fresh mode, all memory cells need to be refreshed before re-entering the self refresh mode again.
 22. XXX: H or L (H: V_{IH} (min) $\leq V_{\text{IN}} \leq V_{\text{IH}}$ (max), L: V_{IL} (min) $\leq V_{\text{IN}} \leq V_{\text{IL}}$ (max))
/////: Invalid Dout
When the address, clock and input pins are not described on timing waveforms, their pins must be applied V_{IH} or V_{IL} .

Timing Waveforms*22

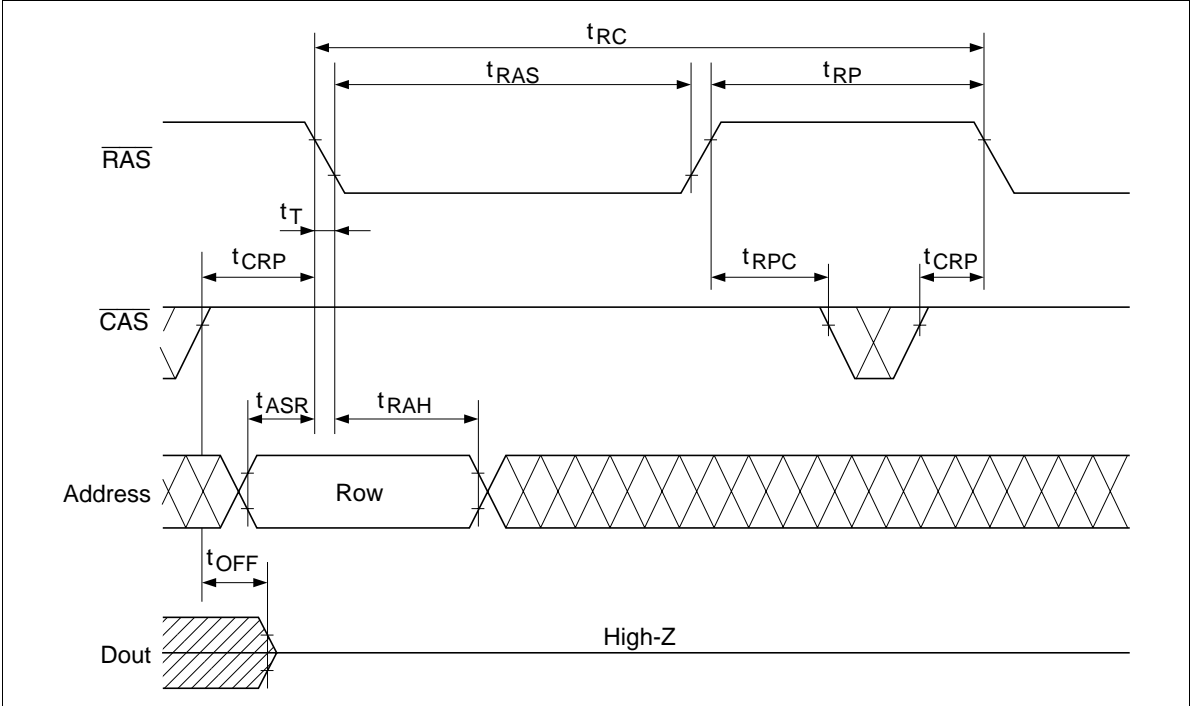
Read Cycle



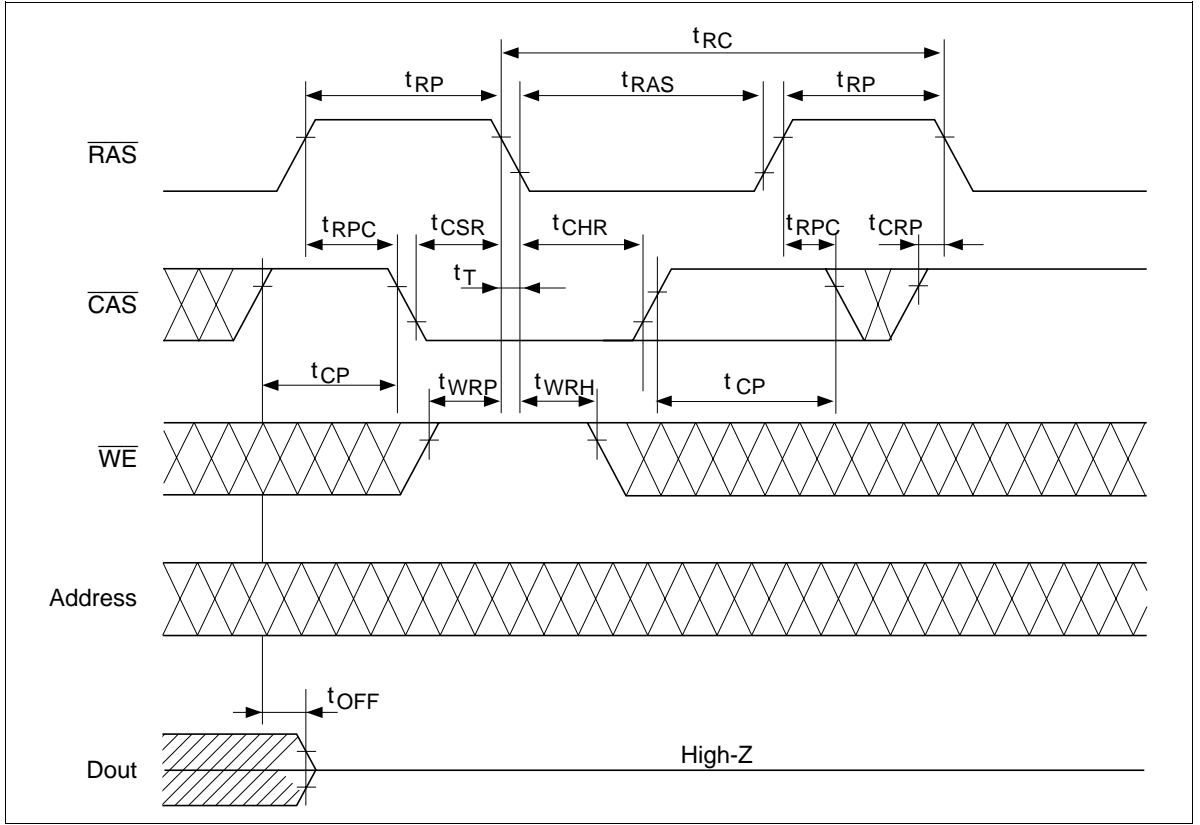
Early Write Cycle



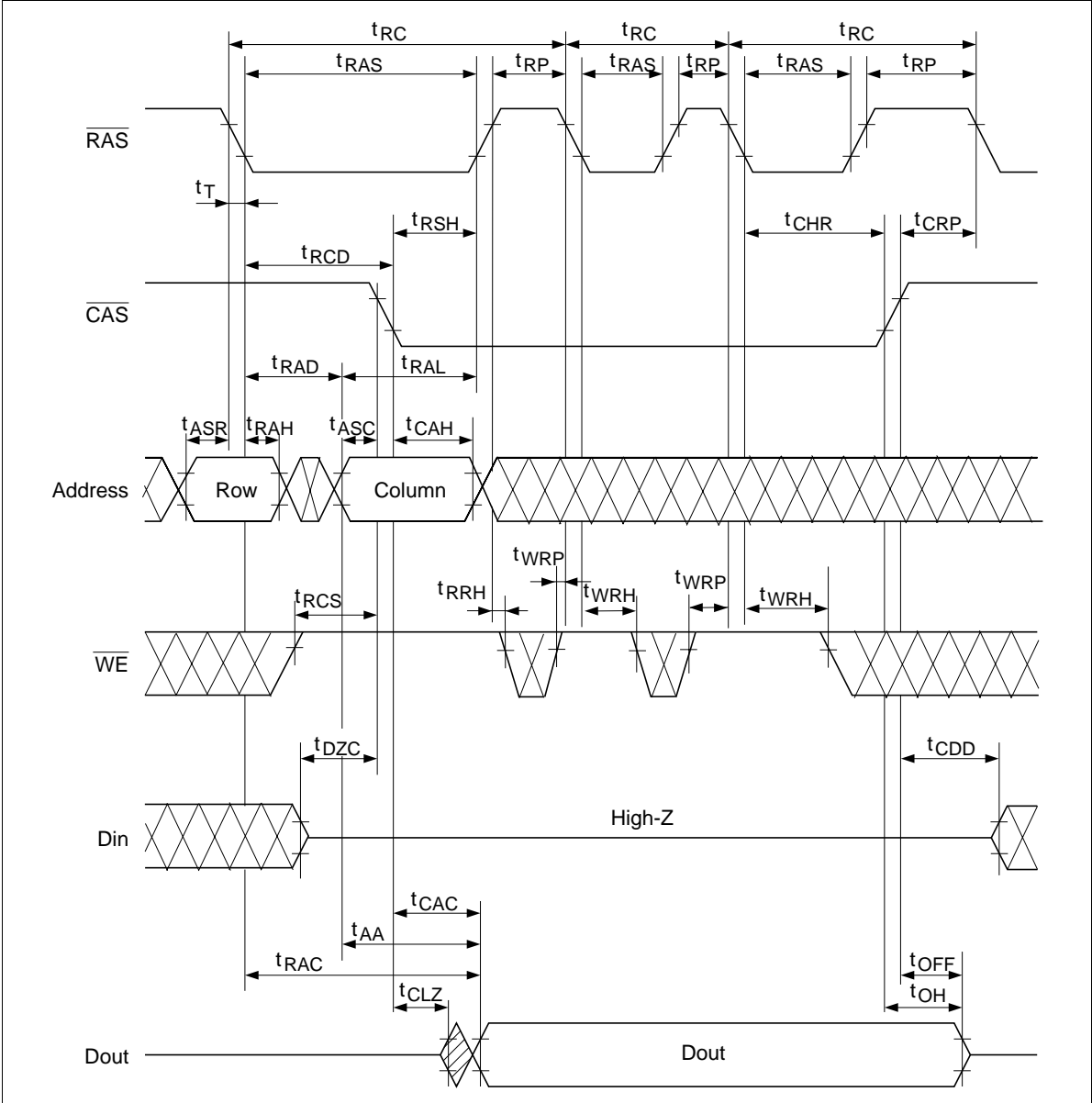
RAS-Only Refresh Cycle



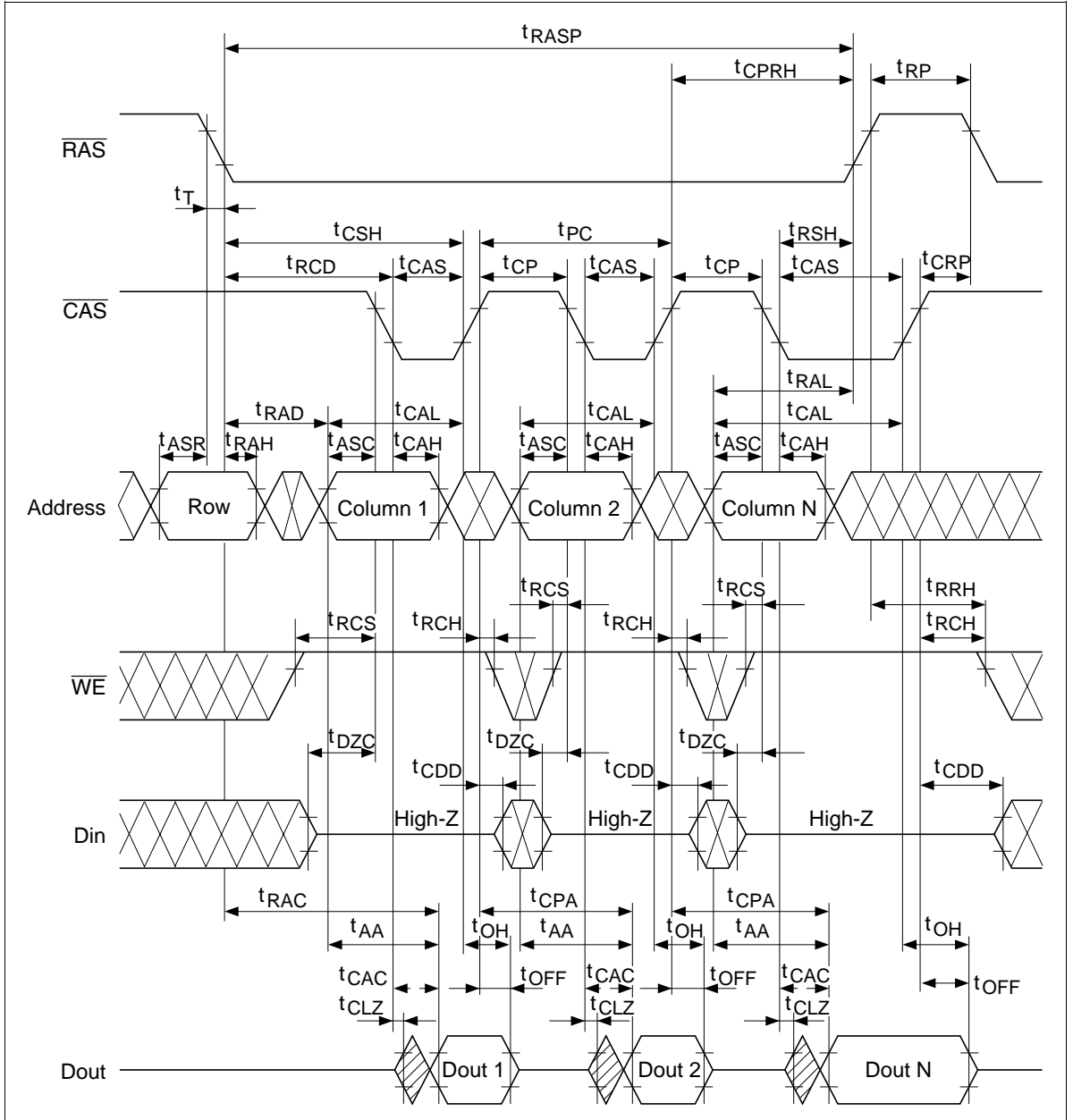
CAS-Before-RAS Refresh Cycle



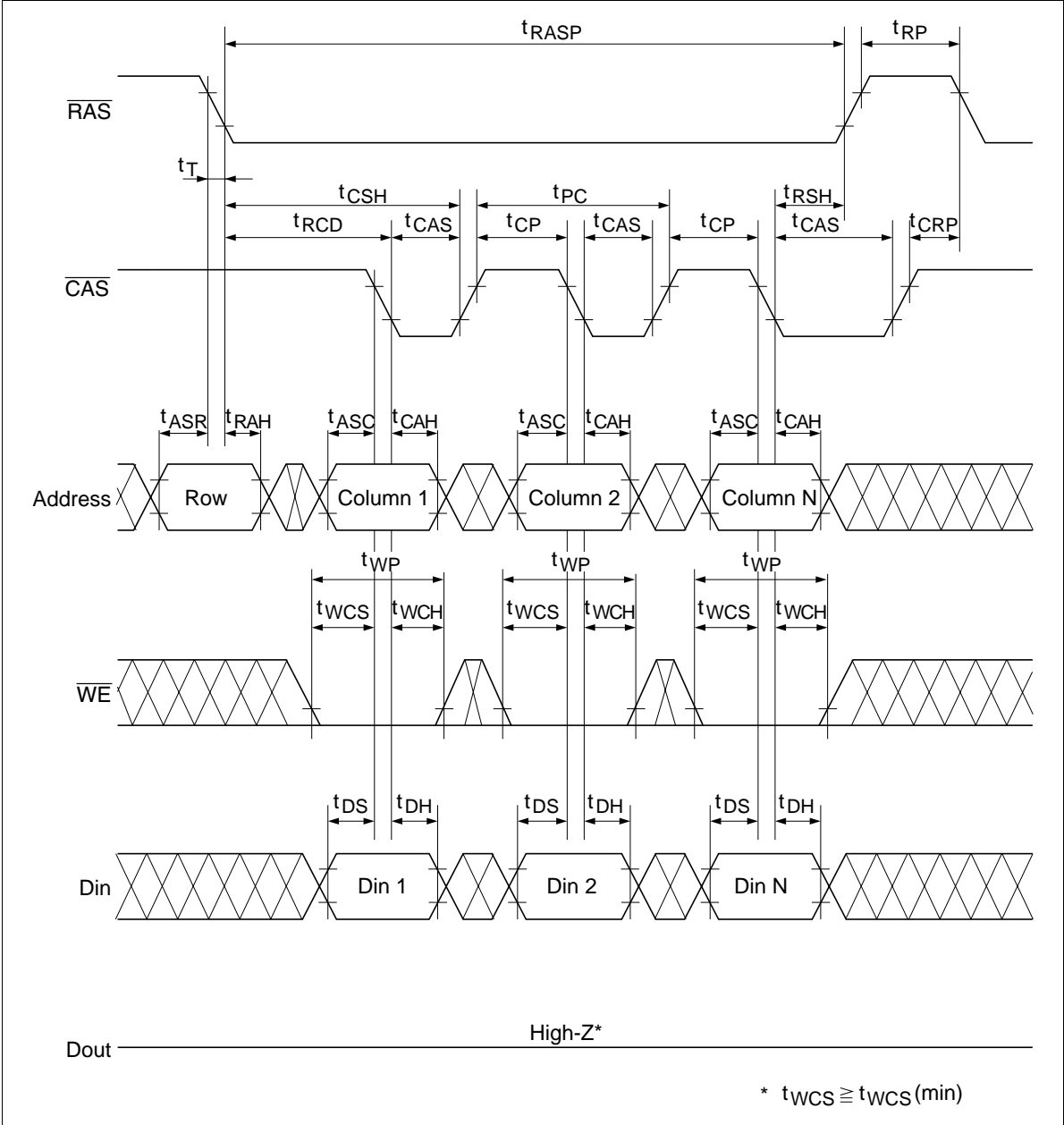
Hidden Refresh Cycle



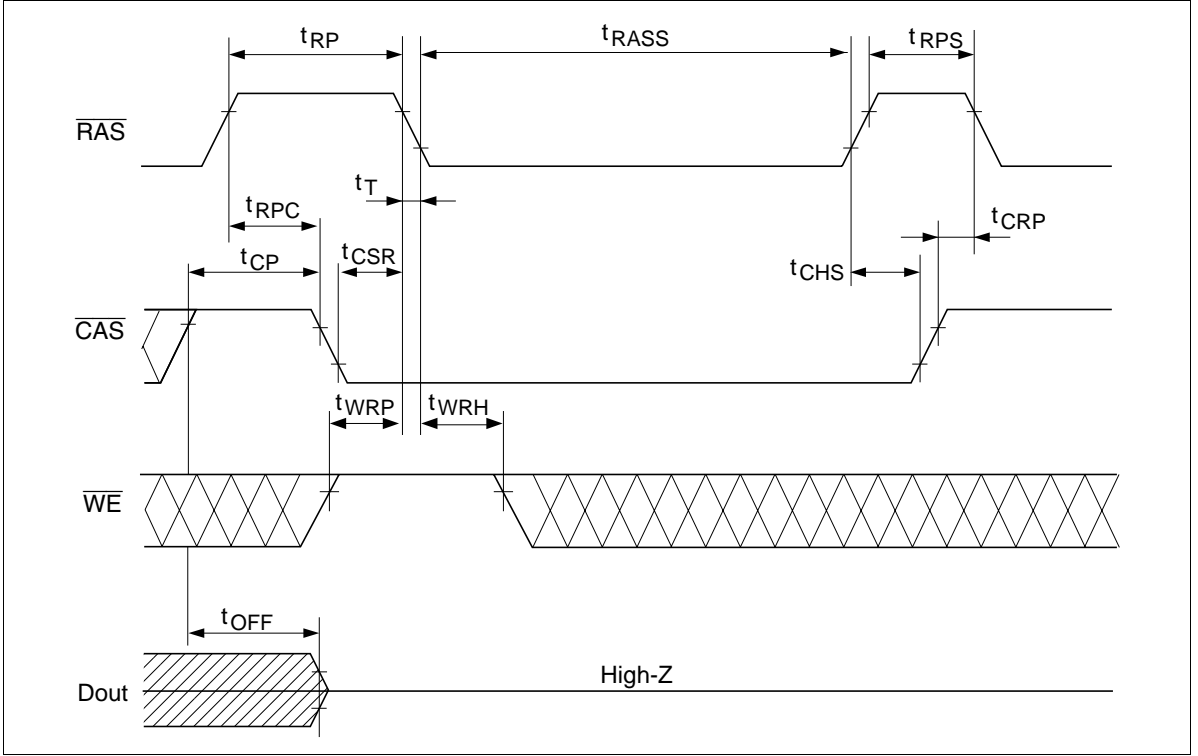
Fast Page Mode Read Cycle



Fast Page Mode Early Write Cycle

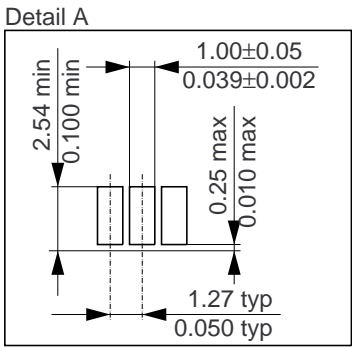
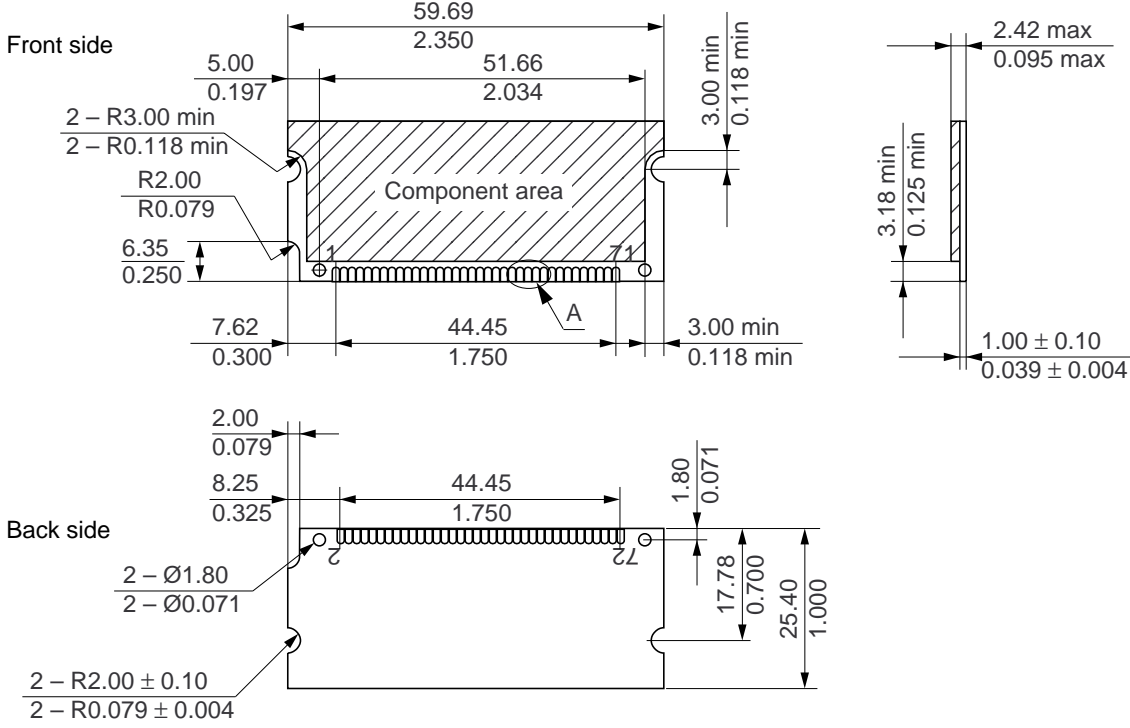


Self Refresh Cycle (L-version)* 18, 19, 20, 21



Physical Outline

Unit : $\frac{\text{mm}}{\text{inch}}$



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HITACHI

Hitachi, Ltd.

Semiconductor & IC Div.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100, Japan
Tel: Tokyo (03) 3270-2111
Fax: (03) 3270-5109

For further information write to:

Hitachi America, Ltd.
Semiconductor & IC Div.
2000 Sierra Point Parkway
Brisbane, CA. 94005-1835
U S A
Tel: 415-589-8300
Fax: 415-583-4207

Hitachi Europe GmbH
Electronic Components Group
Continental Europe
Dornacher Straße 3
D-85622 Feldkirchen
München
Tel: 089-9 91 80-0
Fax: 089-9 29 30 00

Hitachi Europe Ltd.
Electronic Components Div.
Northern Europe Headquarters
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA
United Kingdom
Tel: 0628-585000
Fax: 0628-778322

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 0104
Tel: 535-2100
Fax: 535-1533

Hitachi Asia (Hong Kong) Ltd.
Unit 706, North Tower,
World Finance Centre,
Harbour City, Canton Road
Tsim Sha Tsui, Kowloon
Hong Kong
Tel: 27359218
Fax: 27306071

Revision Record

Rev.	Date	Contents of Modification	Drawn by	Approved by
1.0	Feb. 27, 1997	Initial issue		
